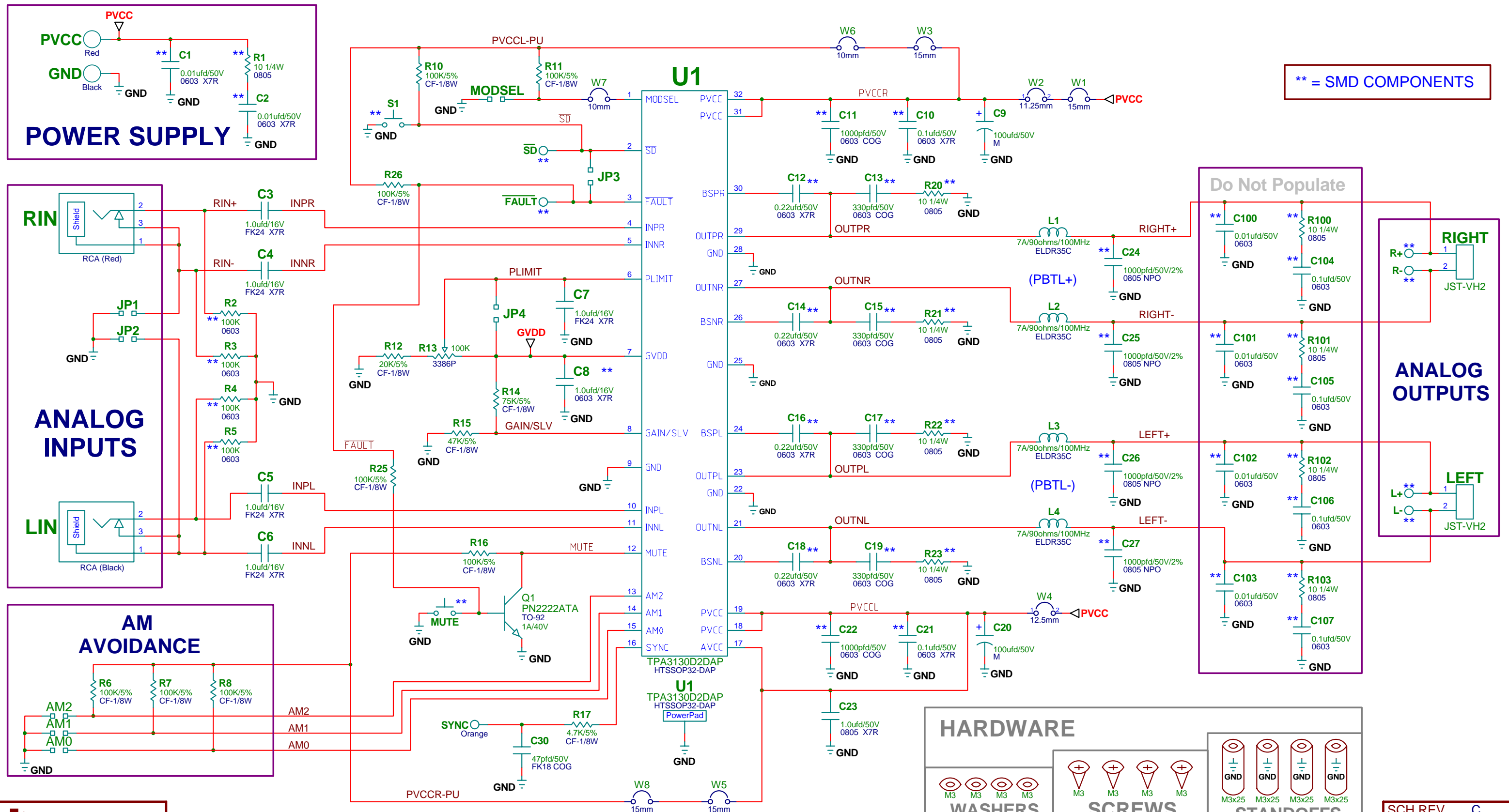


# TPA3130D2DAP EVALUATION BOARD (32Pin Pad Down One Layer Cu)



# TPA3130D2DAP EVALUATION BOARD (32Pin Pad Down One Layer Cu)

REVISION HISTORY			
REVISION	DESCRIPTION	DATE	APPROVAL
A	RELEASE	NOVEMBER 7, 2011	PC
B	1. DELETE C28, C29, C30, C31, C32, C33, C34, C35. 2. DELETE R25, R26, R27, R28. 3. ADD 47K OHM RESISTOR BETWEEN SYNC(TP) AND U1-16. 4. ADD 47pfd CAP BETWEEN SYNC(TP) AND GND. 5. CHANGE R12 TO 20K OHMS.	APRIL 16, 2012	PC
C	1. MOVED R16-2 FROM GND TO PVCCL-PU. 2. ADDED R26(100K,CF-1/8W) TO FAULT NET AND PVCCR-PU NET. 3. ADDED Q1(MMBT2222A) AND CONNECTED AS FOLLOWS: Q1-B TO MUTE SWITCH AND R25 Q1-E TO GND Q1-C TO U1-12.(MUTE NET) 4. ADDED R25(100K,CF-1/8W) TO FAULT NET AND Q1-B.	MAY 25, 2012	PC

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